

REMARKS

Claims 1-4 are pending in this application, of which claim 1 has been amended. No new claims have been added.

Claims 1-4 stand rejected under 35 U.S.C. § 103(a) as unpatentable over **Harumi** in view of **Hajime** (both previously applied).

Applicant respectfully traverses this rejection.

As noted in Applicant's previous response of June 17, 2005, **Harumi** discloses a resin sealed type semiconductor device in which a semiconductor chip 4 is mounted onto one surface of a resin board 3 made of glass-epoxy by a bonding agent having a low thermal expansion coefficient 5. There is a wiring pattern with the exception of a mounting section for the semiconductor chip 4, and there are bonding pads around the mounting section. A resin frame 2 is bonded with the periphery of the bonding pads by a thermo-setting resin having a low thermal expansion coefficient and excellent damp-proofing. Bonding wires 6 are coated with a thermo-setting sealing resin 1' having a thermal expansion coefficient within a range that the bonding wires are not cut by a temperature cycle, and the upper section of the sealing resin 1 and the inside of the resin frame 2 are bonded by a thermo-setting sealing resin 1 having superior damp-proofing. A metallic cap 9 is shaped onto the sealing resin 1.

The Examiner has cited **Hajime** for teaching provision of an electrical connecting portion of at least any of the plurality of electrodes at a reverse face of the semiconductor chip.

Applicant respectfully disagrees.

FIGS. 3 and 4 of Harumi clearly show that the metallic cap 9 fails to cover the lowest peripheral portion of sealing resin 1 (FIG. 3) or the lowest peripheral portion of sealing resin 1' (FIG. 4).

Hajime, which is directed to a high frequency FET, discloses a space 19 provided between SiO₂ film 17 covering the integrated circuit and FET protecting metal film 15, so as not to generate extra capacitance (shown in the paragraph 23). In this way, Hajime, in which space 19 is indispensable, cannot be combined with Harumi to teach the present invention.

The Examiner has noted that Applicant has not claimed that the metal layer is in contact with the resin insulating film, which is not shown in Hajime.

According, claim 1 has been amended to recite this distinction.

Thus, the 35 U.S.C. § 103(a) rejection of claims 1-4 should be withdrawn.

In view of the aforementioned amendments and accompanying remarks, claims 1-4, as amended, are in condition for allowance, which action, at an early date, is requested.

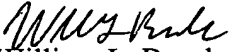
If, for any reason, it is felt that this application is not now in condition for allowance, the Examiner is requested to contact Applicant's undersigned attorney at the telephone number indicated below to arrange for an interview to expedite the disposition of this case.

In the event that this paper is not timely filed, Applicant respectfully petitions for an appropriate extension of time. Please charge any fees for such an extension of time and any other fees which may be due with respect to this paper, to Deposit Account No. 01-2340.

U.S. Patent Application Serial No. **10/659,337**
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Respectfully submitted,

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